

3 (Amended). Thermosettable adhesive according to [any of claims 1-2] claim 1, wherein the thermoformable polymer component comprises one or more polyacrylates, polyesters [and/or], or combinations thereof.

4 (Amended). Thermosettable adhesive according to [any of claims 1-3] claim 1, wherein the thermosettable polymer component comprises one or more [epoxy resins and/or epoxy monomers or oligomers] compounds selected from epoxy monomers, epoxy oligomers, epoxy resins, or combinations thereof.

5 (Amended). Thermosettable adhesive according to [any of claims 1-4] claim 1 which is obtainable by photopolymerization of a precursor comprising:

(i) from about 25 to 60 wt.% of a photopolymerizable, optionally partly prepolymerized mixture comprising at least one acrylic acid ester of a non-tertiary alcohol, and at least one reinforcing, copolymerizable monomer,

(ii) from about 8 to 60 wt.% of one or more compounds selected from epoxy monomers, epoxy oligomers, epoxy resins, or combinations thereof, [epoxy resins and/or epoxy monomers or oligomers containing] wherein the one or more compounds contain no photopolymerizable groups,

(iii) from 0 to about 15 wt.% of one or more additional thermoformable polymers selected from the group comprising polyvinylacetate, poly(ethylene vinyl acetate), polyacetals, polyesters [and/or] poly(caprolactones) or combinations thereof,

(iv) from about 0.1 to 10 wt.% of a heat-activatable curing system for the epoxy component (ii),

(v) from about 0.005 to 3 wt.% of a photoinitiator for the acrylate component (i), and

(vi) from about 0.1 to 20 wt.% of one or more [hydroxides and/or] compounds selected from hydroxides and Al, Mg and Zr, hydroxyoxides of Al, Mg [and/or] and Zr, or combinations thereof;

wherein all weight percentages refer to the mass of the thermosettable adhesive

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7 (Amended). Thermosettable adhesive according to [any of claims 1-6] claim 1 which is obtainable by extrusion of a mixture comprising:

(i) from about 2 to 80 wt.% of one or more polyesters,
(ii) from about 5 to 80 wt.% of one or more [epoxy resins and/or epoxy monomers or oligomers], compounds selected from epoxy monomers, epoxy oligomers, epoxy resins, or combinations thereof,

(iii) from 0 to 15 wt.% of one or more additional thermoformable polymers selected from the group [comprising] consisting of polyacrylate, polyvinylacetate, poly(ethylene vinyl acetate), polyacetals [and/or], poly(caprolactones), or combinations thereof,

(iv) an effective amount of one or more heat-activatable [and/or] or one or more photoactivatable curing systems, or combinations thereof, for the epoxy component (ii),

(v) from about 0.1 to 20 wt.% of one or more [hydroxides and/or] compounds selected from hydroxides of Al, Mg and Zr, hydroxyoxides of Al, Mg [and/or] and Zr, or combinations thereof,

wherein the onset temperature of the curing reaction of the epoxy component (ii) is higher than the extrusion temperature and wherein all weight percentages refer to the mass of the thermosettable adhesive.

8 (Amended). Thermosettable adhesive tape comprising at least one layer of a thermosettable adhesive according to [any of claims 1-7] claim 1, wherein such layer has at least one exposed surface and optionally comprises a backing.

9 (Amended). [Use of the thermosettable] Thermosettable adhesive [of any of claims 1-7] according to claim 1, wherein the adhesive is utilized for melt sealing or bonding applications.